



Material Content Data Sheet



Sales Product Name		BSP752R		Issued		31. January 2019		
MA#		MA001425968						
Package		PG-DSO-8-24		Weight*		83.33 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.188	2.63	2.63	26260	26260
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8607	
wire	non noble metal	copper	7440-50-8	29.121	34.95	35.86	349483	358628
	noble metal	gold	7440-57-5	0.426	0.51	0.51	5116	5116
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1167
plastics	plastics	epoxy resin	-	4.473	5.37		53682	
	inorganic material	silicondioxide	60676-86-0	44.051	52.85	58.34	528652	583501
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9767	9767
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7804	7804
glue	plastics	epoxy resin	-	0.130	0.16		1562	
	noble metal	silver	7440-22-4	0.613	0.74	0.90	7362	8924
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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